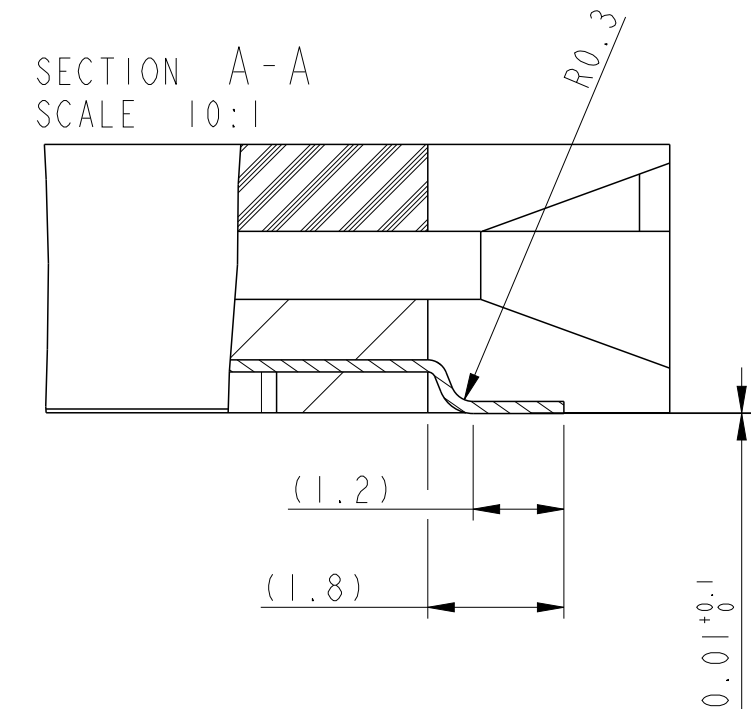
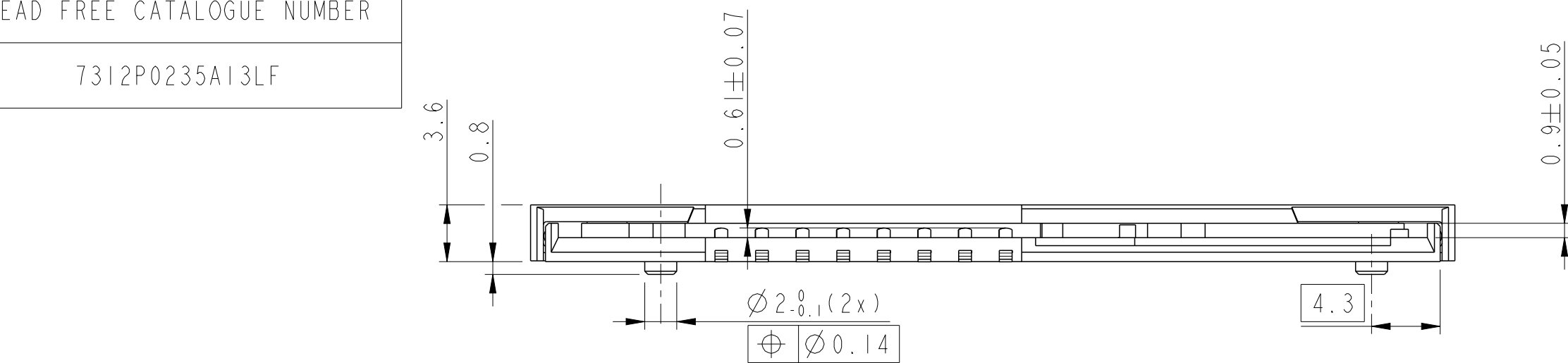


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DESCRIPTION
Connector especially designed for SMT technology
EMV compatible and in accordance with ISO 7816-2

MECHANICAL
Contacts force : between 0.2N-0.5N
Durability : 100000 cycles
Insertion force : 10N max
Extraction force : 3N min

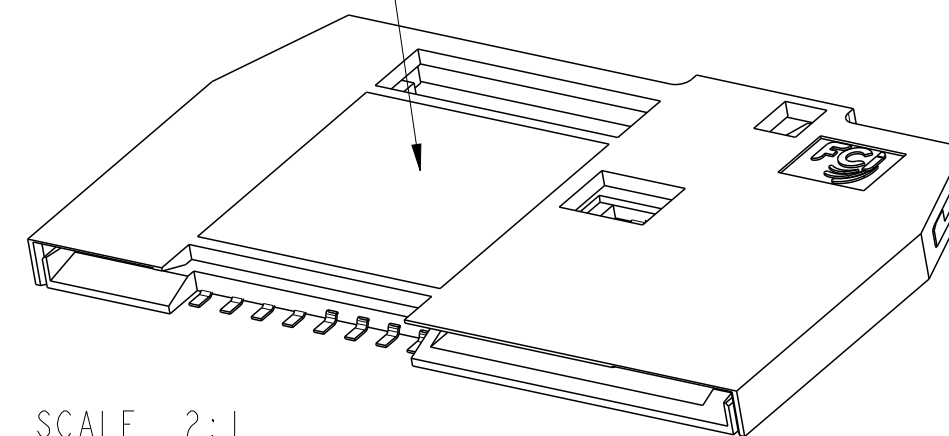
ELECTRICAL
Insulation resistance : 1000MOhms
Dielectric withstand voltage between card contacts and detection switch : 1000 Vrms
contact resistance:100 miliohms
Current carrying : min 10 microA max 1A

SWITCH
Contact closed : contact resistance 100mOhms
Open contact : voltage proof 300Vms

MATERIAL
Contacts : copper alloy
Plating : Gold / Equivalent PdNi over Nickel on contact area
Solder falls : Sn bare edge allowed
Housing : self extinguishing, Thermoplastic
UL94-V0 rated

ENVIRONMENT
Storage temperature : -40°C, +85°C
Operating temperature : -20°C, +70°C
Packaging : Tray
Compatible reflow soldering process

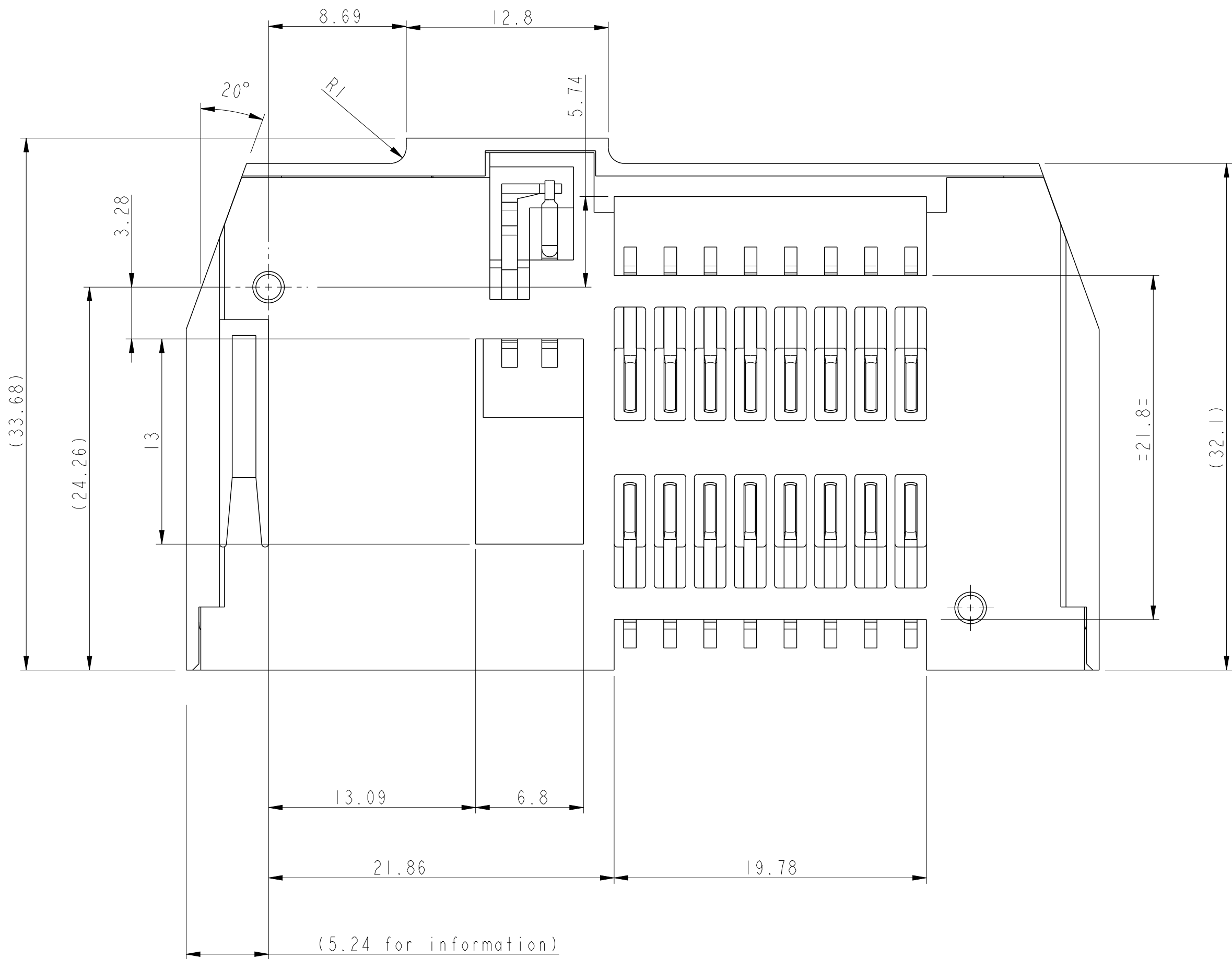
Pick and place area



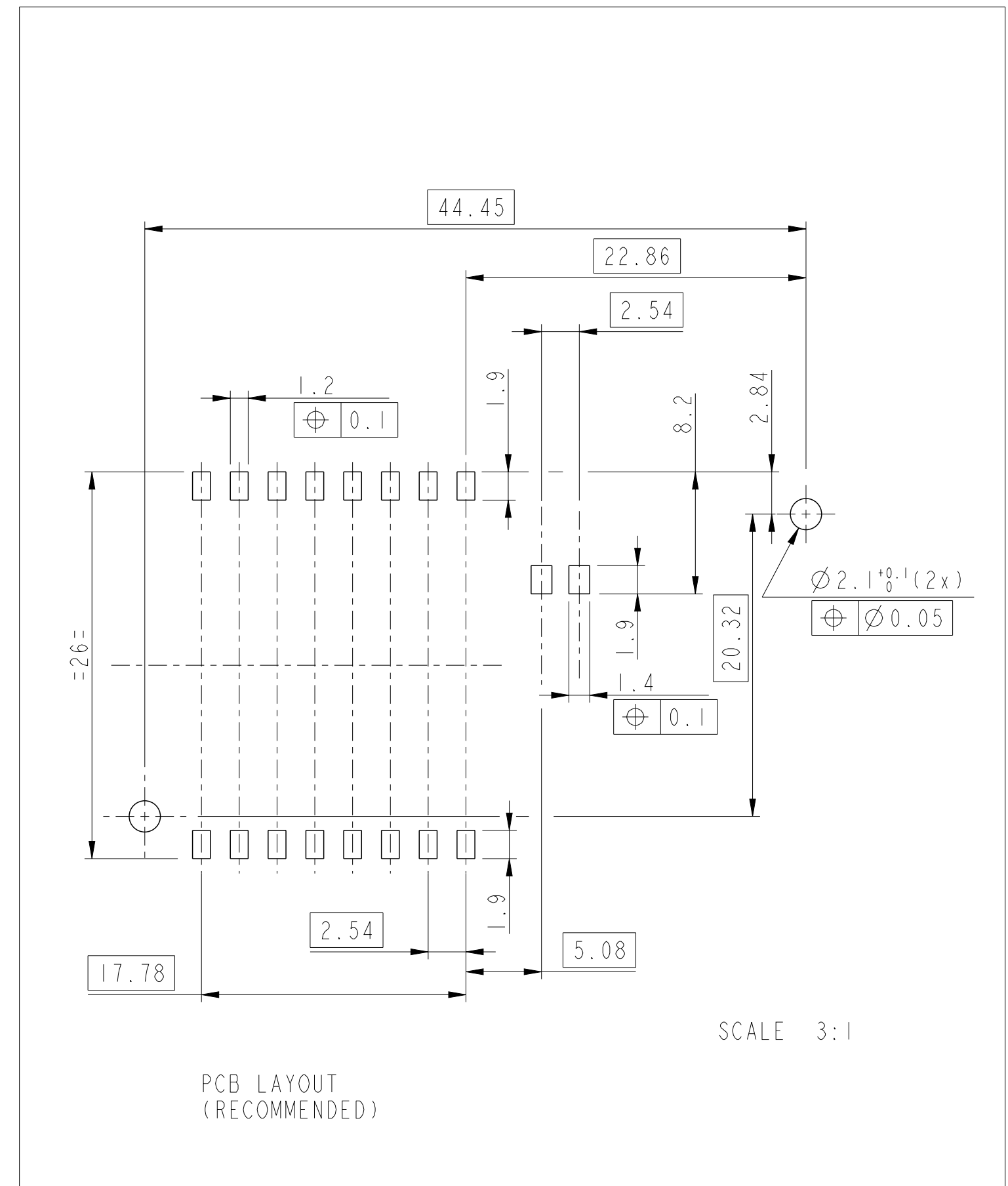
www.fciconnect.com				surface -- ✓		tolerance std		projection		mm	
				ISO 1302		ISO 406 ISO 1101					
				TOLERANCES UNLESS OTHERWISE SPECIFIED							
Dr		LEGRAND		1996/08/26		ANGULAR		LINEAR		Scale	
Eng		TISSERAND		1996/08/26				0.X		±0.3	
Chr		RAMESH P K		2007/02/26		0° ±2°		0.XX		±0.1	
Appr		SUDHIR V		2007/02/26				0.XXX		±0.05	
						Product family		MOBILE I/O		ECN 109-0239	
										Spec ref --	
A		LS2030		PRI		2002/04/26					
B		--		--		--					
C		LS05-0047		LGO		2005/06/08					
D		LS05-0059		HLE		2005/06/30					
E		LS06-0208		HLE		2006/12/12					
F		108-0035		RPK		2008/03/07					
G		109-0239		RPK		2009/10/30					

	CHIP CARD CONNECTOR				dwg no	VJW53665		Rev. F	
	TYPE : P02 (16cts with cover)								
	catalog no		7312P0235A13			CUSTOMER			
								sheet 1 of 2	

LEAD FREE CATALOGUE NUMBER
7312P0235A13LF

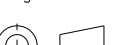


LAYOUT FOR KEEP OUT ZONE
(CONNECTOR SIDE)



NOTE: RoHS INFORMATION

- The "LF" products meet European Union Directives and other country regulations as described in GS-22-008.
- The housing will withstand exposure to 260°C peak temperature for 30 seconds in a convection, infra-red or vapor reflow oven. See Application notes/procedures, if they are available.
- Packaging spec: see GS-14-920

www.fciconnect.com			surface -- 		tolerance std ISO 1302 ISO 406 ISO 1101		projection 		mm 		
			TOLERANCES UNLESS OTHERWISE SPECIFIED								
Dr	LEGRAND	1996/08/26	ANGULAR	LINEAR	0.X	±0.3	size A2	Scale 4:1			
Eng	TISSERAND	1996/08/26			0.XX	±0.1					
Chr	RAMESH P K	2007/02/26	0°	±2°	0.XXX	±0.05	ECN		109-0239		
Appr	SUDHIR V	2007/02/26	Product family MOBILE I/O				Spec ref		--		
			title CHIP CARD CONNECTOR				dwg no VJW53665		Rev. F		
			TYPE : P02 (16cts with cover)								
catalog no 7312P0235A13				CUSTOMER				sheet 2 of 2			